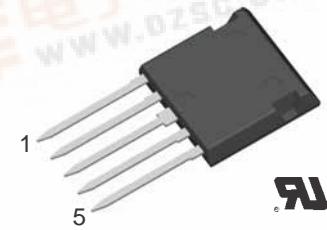
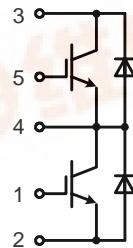




FII 50-12E

## NPT<sup>3</sup> IGBT phaseleg in ISOPLUS i4-PAC™

**I<sub>C25</sub>** = 50 A  
**V<sub>CES</sub>** = 1200 V  
**V<sub>CE(sat)</sub> typ.** = 2.0 V



### IGBTs

| Symbol                              | Conditions   | Maximum Ratings |    |                  |
|-------------------------------------|--|-----------------|----|------------------|
| V <sub>CES</sub>                    | T <sub>VJ</sub> = 25°C to 150°C  | 1200            | V  |                  |
| V <sub>GES</sub>                    |  | ± 20            | V  |                  |
| I <sub>C25</sub>                    | T <sub>C</sub> = 25°C  | 50              | A  |                  |
| I <sub>C90</sub>                    | T <sub>C</sub> = 90°C  | 32              | A  |                  |
| I <sub>CM</sub><br>V <sub>CEK</sub> | { V <sub>GE</sub> = ±15 V; R <sub>G</sub> = 39 Ω; T <sub>VJ</sub> = 125°C<br>RBSOA, Clamped inductive load; L = 100 μH | 50              | A  | V <sub>CES</sub> |
| t <sub>sc</sub><br>(SCSOA)          | V <sub>CE</sub> = 900V; V <sub>GE</sub> = ±15 V; R <sub>G</sub> = 39 Ω; T <sub>VJ</sub> = 125°C<br>non-repetitive      | 10              | μs |                  |
| P <sub>tot</sub>                    | T <sub>C</sub> = 25°C  | 200             | W  |                  |

| Symbol   | Conditions  | Characteristic Values                                |                   |                                  |
|--|---|--|-------------------|----------------------------------|
|  |   | (T <sub>VJ</sub> = 25°C, unless otherwise specified) | min.              | typ.                             |
| V <sub>CE(sat)</sub>   | I <sub>C</sub> = 30 A; V <sub>GE</sub> = 15 V; T <sub>VJ</sub> = 25°C<br>T <sub>VJ</sub> = 125°C  | 2.0  | 2.6               | V                                |
|  |   | 2.3  |                   | V                                |
| V <sub>GE(th)</sub>  | I <sub>C</sub> = 1 mA; V <sub>GE</sub> = V <sub>CE</sub>  | 4.5  |                   | V                                |
| I <sub>CES</sub>   | V <sub>CE</sub> = V <sub>CES</sub> ; V <sub>GE</sub> = 0 V; T <sub>VJ</sub> = 25°C<br>T <sub>VJ</sub> = 125°C                                 |  | 0.4               | mA                               |
| I <sub>GES</sub>   | V <sub>CE</sub> = 0 V; V <sub>GE</sub> = ± 20 V   |  | 200               | nA                               |
| t <sub>d(on)</sub><br>t <sub>r</sub><br>t <sub>d(off)</sub><br>t <sub>f</sub><br>E <sub>on</sub><br>E <sub>off</sub> | { Inductive load, T <sub>VJ</sub> = 125°C<br>V <sub>CE</sub> = 600 V; I <sub>C</sub> = 30 A<br>V <sub>GE</sub> = ±15 V; R <sub>G</sub> = 39 Ω | 85<br>50<br>440<br>50<br>4.6<br>2.2                  |                   | ns<br>ns<br>ns<br>ns<br>mJ<br>mJ |
| C <sub>ies</sub><br>Q <sub>Gon</sub>   | V <sub>CE</sub> = 25 V; V <sub>GE</sub> = 0 V; f = 1 MHz<br>V <sub>CE</sub> = 600 V; V <sub>GE</sub> = 15 V; I <sub>C</sub> = 30 A            | 2<br>250   |                   | nF<br>nC                         |
| R <sub>thJC</sub><br>R <sub>thJH</sub>   | with heatsink compound  | 1.2  | 0.6<br>K/W<br>K/W |                                  |

### Features

- NPT<sup>3</sup> IGBT
  - low saturation voltage
  - positive temperature coefficient for easy paralleling
  - fast switching
  - short tail current for optimized performance in resonant circuits
- HiPerFRED™ diode
  - fast reverse recovery
  - low operating forward voltage
  - low leakage current
- ISOPLUS i4-PAC™ package
  - isolated back surface
  - enlarged creepage towards heatsink
  - application friendly pinout
  - low inductive current path
  - high reliability
  - industry standard outline
  - UL registered, E 72873

### Applications

- single phaseleg
  - buck-boost chopper
- H bridge
  - power supplies
  - induction heating
  - four quadrant DC drives
  - controlled rectifier
- three phase bridge
  - AC drives
  - controlled rectifier

**Diodes**

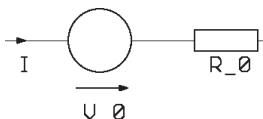
| Symbol    | Conditions         | Maximum Ratings |   |  |
|-----------|--------------------|-----------------|---|--|
| $I_{F25}$ | $T_C = 25^\circ C$ | 48              | A |  |
| $I_{F90}$ | $T_C = 90^\circ C$ | 25              | A |  |

| Symbol                                 | Conditions   | Characteristic Values |                |      |
|--|--|-----------------------|----------------|------|
|  |  | min.                  | typ.           | max. |
| $V_F$                                  | $I_F = 30 A; T_{VJ} = 25^\circ C$<br>$T_{VJ} = 125^\circ C$                                | 2.4<br>1.8            | 2.8<br>V<br>V  |      |
| $I_{RM}$<br>$t_{rr}$<br>$E_{rec(off)}$ | $I_F = 30 A; di_F/dt = -1100 A/\mu s; T_{VJ} = 125^\circ C$<br>$V_R = 600 V; V_{GE} = 0 V$ | 51<br>180<br>1.8      | A<br>ns<br>mJ  |      |
| $R_{thJC}$<br>$R_{thJS}$               | (per diode)  | 1.6                   | 1.3 K/W<br>K/W |      |

**Component**

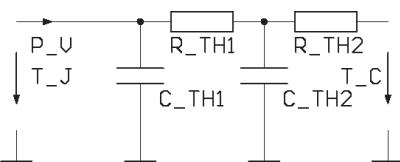
| Symbol     | Conditions                     | Maximum Ratings |    |    |
|------------|--------------------------------|-----------------|----|----|
| $T_{VJ}$   |                                | -55...+150      |    | °C |
| $T_{stg}$  |                                | -55...+125      |    | °C |
| $V_{ISOL}$ | $I_{ISOL} \leq 1 mA; 50/60 Hz$ | 2500            | V~ |    |
| $F_c$      | mounting force with clip       | 20...120        | N  |    |

| Symbol                 | Conditions                        | Characteristic Values |      |          |
|------------------------|-----------------------------------|-----------------------|------|----------|
|                        |                                   | min.                  | typ. | max.     |
| $d_s d_A$<br>$d_s d_A$ | pin - pin<br>pin - backside metal | 1.7<br>5.5            |      | mm<br>mm |
| Weight                 |                                   | 9                     |      | g        |

**Equivalent Circuits for Simulation**
**Conduction**


IGBT (typ. at  $V_{GE} = 15 V; T_J = 125^\circ C$ )  
 $V_0 = 0.95 V; R_0 = 45 m\Omega$

Diode (typ. at  $T_J = 125^\circ C$ )  
 $V_0 = 1.26 V; R_0 = 15 m\Omega$

**Thermal Response**

**IGBT**

$$C_{th1} = 0.067 J/K; R_{th1} = 0.108 K/W$$

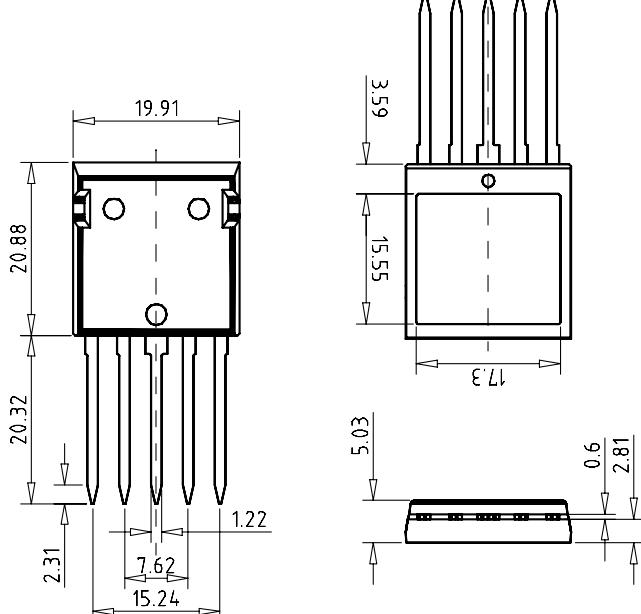
$$C_{th2} = 0.175 J/K; R_{th2} = 0.491 K/W$$

**Diode**

$$C_{th1} = 0.039 J/K; R_{th1} = 0.337 K/W$$

$$C_{th2} = 0.090 J/K; R_{th2} = 0.963 K/W$$

Dimensions in mm (1 mm = 0.0394")



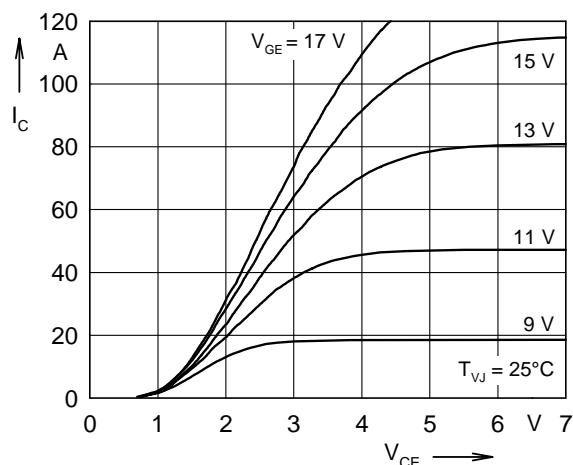


Fig. 1 Typ. output characteristics

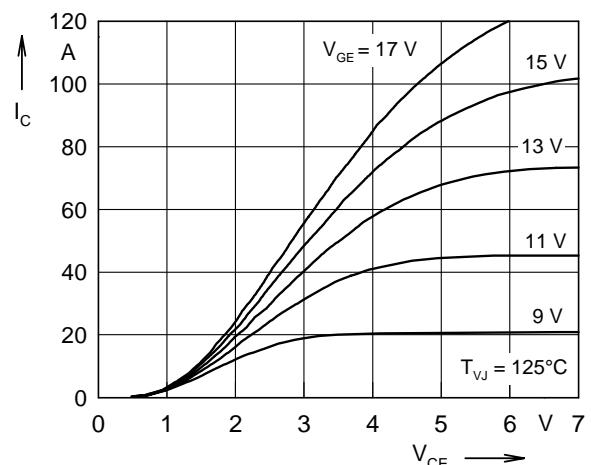


Fig. 2 Typ. output characteristics

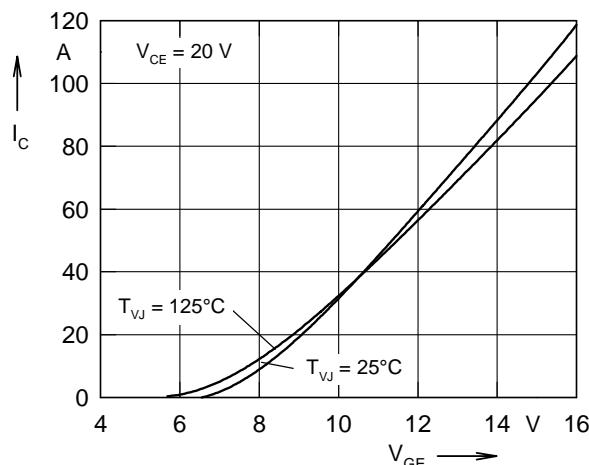


Fig. 3 Typ. transfer characteristics

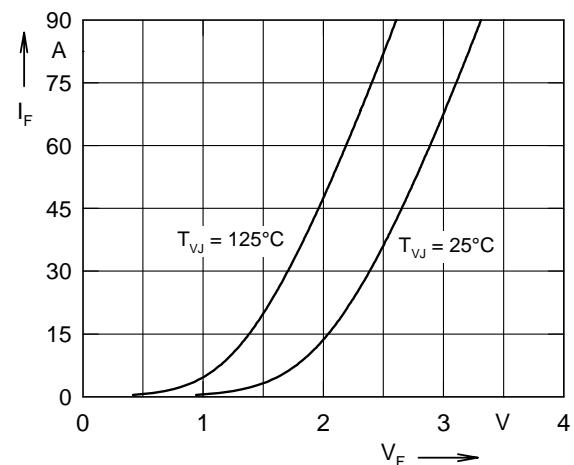


Fig. 4 Typ. forward characteristics of free wheeling diode

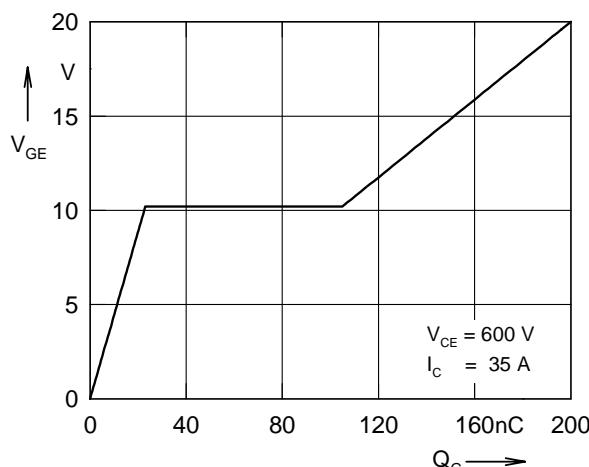


Fig. 5 Typ. turn on gate charge

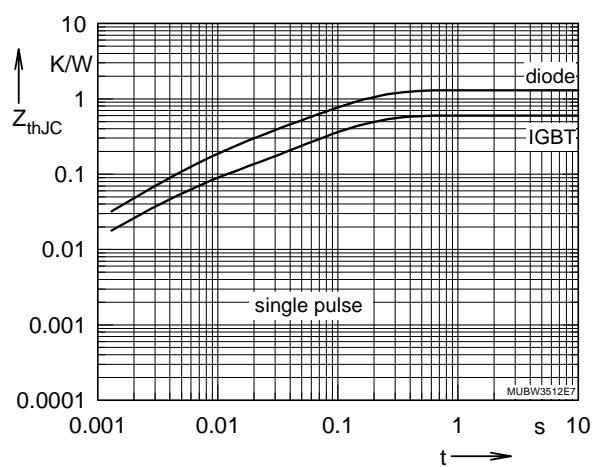


Fig. 6 Typ. transient thermal impedance

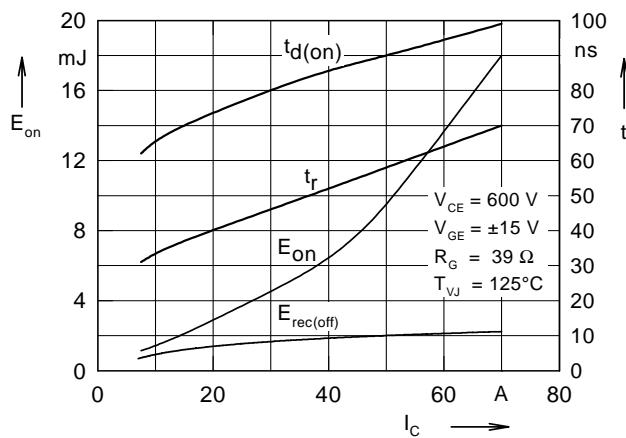


Fig. 7 Typ. turn on energy and switching times versus collector current

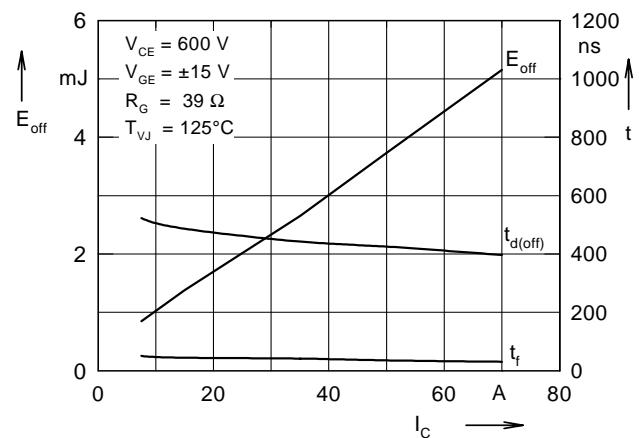


Fig. 8 Typ. turn off energy and switching times versus collector current

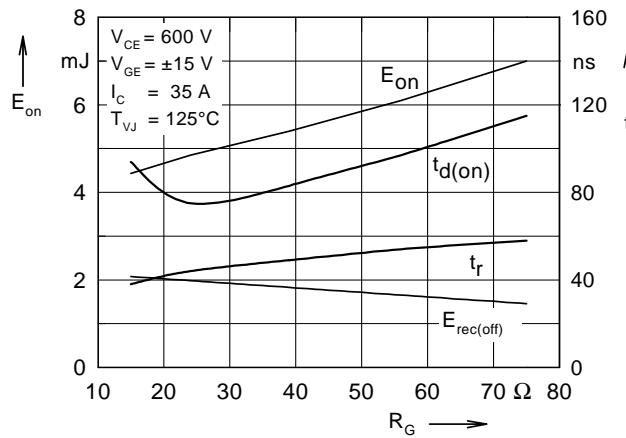


Fig. 9 Typ. turn on energy and switching times versus gate resistor

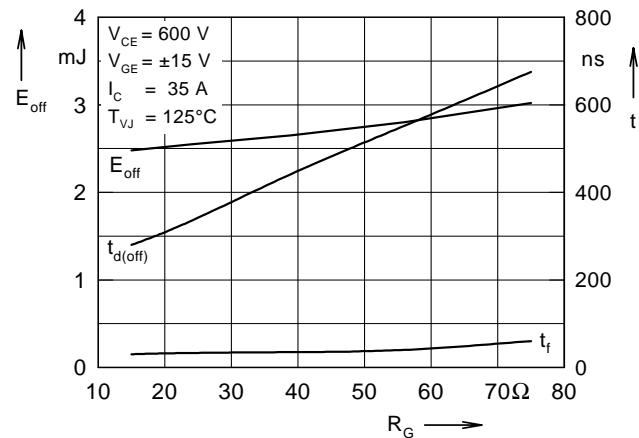


Fig. 10 Typ. turn off energy and switching times versus gate resistor

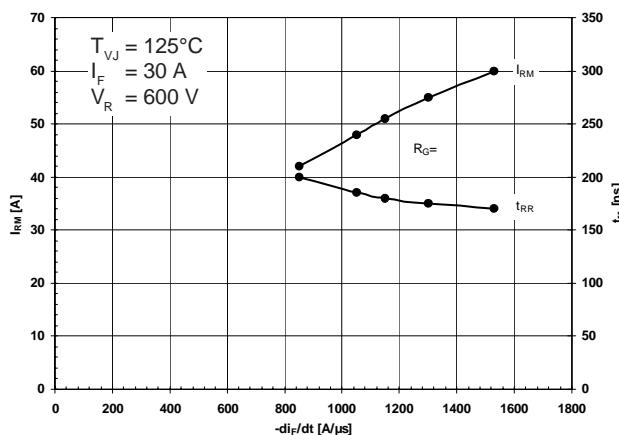


Fig. 11 Typ. turn off characteristics of free wheeling diode

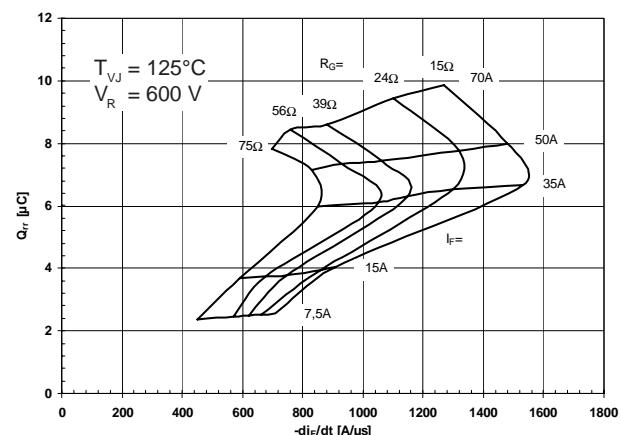


Fig. 12 Typ. turn off characteristics of free wheeling diode